an elastic contact force (30,32) to at least one of said components (22) of said electromechanical transducer, forming a mechanical contact.

Amend claim 5 as follows:

--5. (Amended) The transducer microsystem according to claim 1, characterised by electrical components (24) and/or optical components attached to said flexible printed circuit board (10).

Amend claim 7 as follows:

--7. (Amended) The transducer microsystem according to claim 3, characterised in that said elastic deformation comprises an elastic compression or tension substantially perpendicular to the surface of said flexible printed circuit board (10).

Amend claim 9 as follows:

--9. (Amended) The transducer microsystem according to claim 3, characterised in that said elastic deformation comprises an elastic deflection of at least a portion (19) of said flexible printed circuit board (10).

Amend claim 11 as follows:

--11. (Amended) The transducer microsystem according to claim 9, characterised in that a first component (22) of said electromechanical transducer is positioned in the path of said elastic deflection, whereby the resil-

ience of said deflected flexible printed circuit board portion (19) applies a spring force on said first component (22) of said electromechanical transducer.

Amend claim 12 as follows:

--12. (Amended) The transducer microsystem according to claim 1, characterised in that said flexible printed circuit board (10) constitutes a casing of said transducer microsystem.

Amend claim 13 as follows:

--13. (Amended) The transducer microsystem according to claim 1, characterised in that said flexible printed circuit board (10) comprises polyimide material.

Amend claim 14 as follows:

--14. (Amended) The transducer microsystem according to claim 1, characterised in that said flexible printed circuit board (10) is provided with geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48), which are engagable to other ones of said geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) and/or to other members of said transducer microsystem.

Amend claim 16 as follows:

--16. (Amended) The transducer microsystem according to claim 14, characterised in that said geometri-

cal structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) comprise adjustable locking structures.

Amend claim 17 as follows:

--17. (Amended) A microelectromechanical motor, comprising a transducer microsystem according to claim 1.

Amend claim 21 as follows:

--21. (Amended) The method of assembling a transducer microsystem according to claim 19, characterised by the further step of attaching electrical components (24) and/or optical components to said flexible printed circuit board (10).

Amend claim 22 as follows:

--22. (Amended) The method of assembling a transducer microsystem according to claim 19, characterised in that at least the major part of any steps of attaching components (22, 24, 26) to said flexible printed circuit are performed on a substantially flat flexible printed circuit board (10).

Amend claim 23 as follows:

--23. (Amended) The method of assembling a transducer microsystem according to claim 19, characterised by the further step of providing said flexible printed circuit board (10) with geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48), which are engagable to

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other ones of said geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) and/or to other member of said transducer microsystem.

Amend claim 26 as follows:

--26. (Amended) The method of assembling a transducer microsystem claim 20, characterised in that said step of reshaping comprises at least one of the following steps;

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elastically folding said flexible printed circuit (10);

elastically bending said flexible printed circuit (10); and

elastically tensing or compressing said flexible printed circuit (10) substantially perpendicular to its surface.--